PROCESS FOR MANUFACTURING CIRCUIT BOARD AND CIRCUIT BOARD

ABSTRACT

According to the present invention, there is provided a process for manufacturing a circuit board wherein a first substrate having a conductor post and a second substrate having a conductor pad for receiving the conductor post are laminated through an interlayer adhesive, and the conductor post and the conductor pad are electrically connected, comprising, as a first step, bonding the conductor pad with the conductor post by thermocompression under predetermined first conditions while the first and the second substrates are arranged such that the conductor pad faces the conductor post through the interlayer adhesive; thermocompressing the first substrate and the second substrate under predetermined second conditions while the conductor pad is bonded with the conductor post; and thermocompressing the first substrate and the second substrate under predetermined third conditions while the conductor pad is bonded with the conductor post, wherein the first, the second and the third conditions are different from each other.

FIG. 4